

**IN THE CLAIMS:**

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~strikethrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

1-3. (Cancelled)

4. (currently amended) ~~The~~A semiconductor device having a plurality of wiring layers on which a dummy pattern and an actual pattern are arranged,  
wherein said dummy pattern has a rectangular shape and is arranged by rotating a given angle in a direction in which said actual pattern extends~~according to claim 3, and~~  
wherein longer sides of said dummy pattern extend in a same direction as said actual pattern which is perpendicularly wired extends.

5. (currently amended) ~~The~~A semiconductor device having a plurality of wiring layers on which a dummy pattern and an actual pattern are arranged,  
wherein said dummy pattern has a rectangular shape and is arranged by rotating a given angle in a direction in which said actual pattern extends~~according to claim 3, and~~  
wherein longer sides of said dummy pattern extend perpendicularly to the direction in which said actual pattern extends.

6. (Original) The semiconductor device according to claim 5,  
wherein said actual pattern is perpendicularly wired.

7. (currently amended) The semiconductor device according to claim ~~3~~4,  
wherein positions of center points of said dummy patterns of said plurality of wiring layers vary for respective wiring layers.

8. (currently amended) The semiconductor device according to claim ~~3~~5,  
wherein positions of center points of said dummy patterns of said plurality of wiring layers vary for respective wiring layers and respective longer sides of said dummy patterns on different wiring layers extend parallel to each other.

9. (currently amended) The semiconductor device according to claim 35, wherein respective longer sides of said dummy patterns on adjacent wiring layers extend perpendicularly to each other.

10-15. (Cancelled)

16. (New) The semiconductor device according to claim 5, wherein positions of center points of said dummy patterns of said plurality of wiring layers vary for respective wiring layers.